Processing guideline for *FARADFLEX*



Ver.2

Product Data

Electrical Property

Characteristics	Condition	Unit	*BC 24*	*BC 16*	*BC 12*
Capacitance	1GHz	pF/in2	900	1500	2000
Dk	1GHz	N/A	4.6	4.6	4.6
Df	1GHz	N/A	0.012	0.012	0.012
Dielectric Thickness	Nominal	Micron Meter	24	16	12

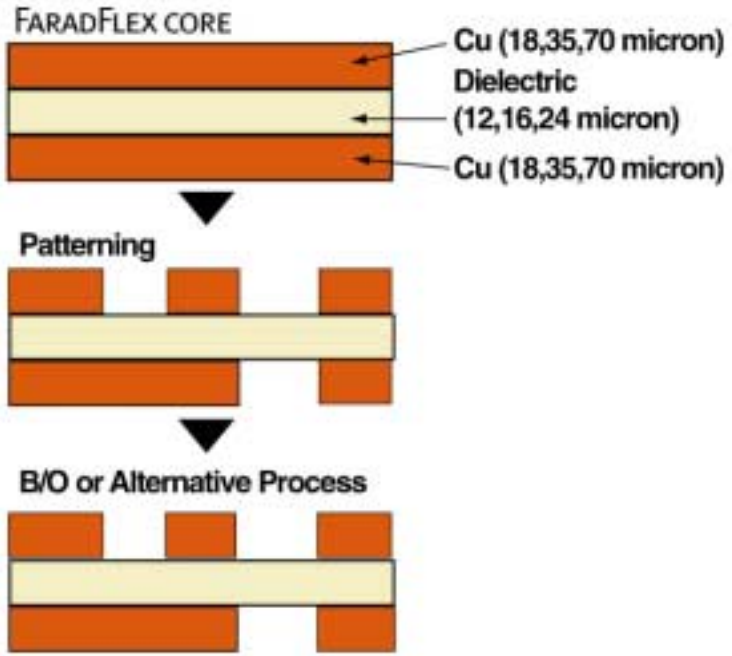
Product Data

Physical Property

Characteristics	Condition	Unit	*BC 24*	*BC 16*	*BC 12*
Tg	DMA	Celsius	200	200	200
Peel Strength	As received	lb/in	>6.0	>6.0	>6.0
Young's Modules	JIS 2318	GPa	4.8	5.8	7.2
Tensile Strength	JIS 2318	MPa	180	180	180
CTE	IPC TM650	PPM	30	30	30
Breakdown	1kV/sec	V	>5000	>4000	>4000
Insulation Reliability	85C/85%/35V	hr	>1000	>1000	>1000

Processing guideline

1. **Pre-clean**
   - Standard process
2. **Dry Film lamination**
   - Standard process
3. **Expose Image**
   - Standard process
4. **Pattern etching (Dual sides)**
   - Thin core compatible line recommended
     Ex) Thin core Schmid etching line
   - Use leader board if not confident
   - Careful Handling required
5. **Black oxidizing or alternative oxides**
   - Thin core compatible line recommended
   - Use leader board if not confident
   - Horizontal line preferred
   - Careful Handling required



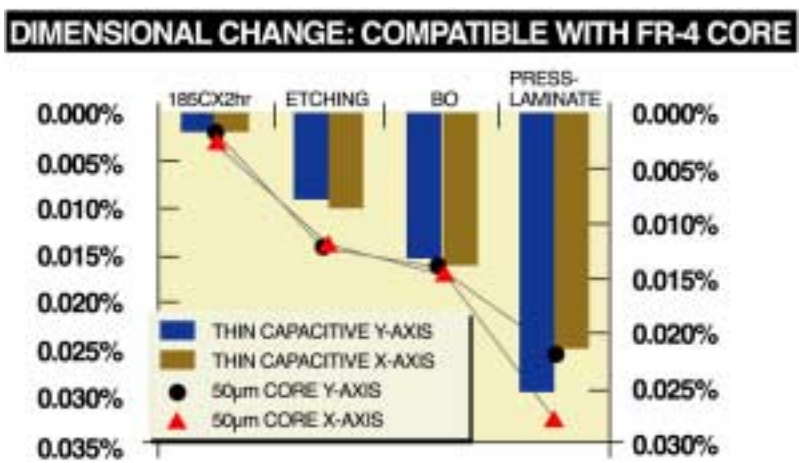
Processing guideline

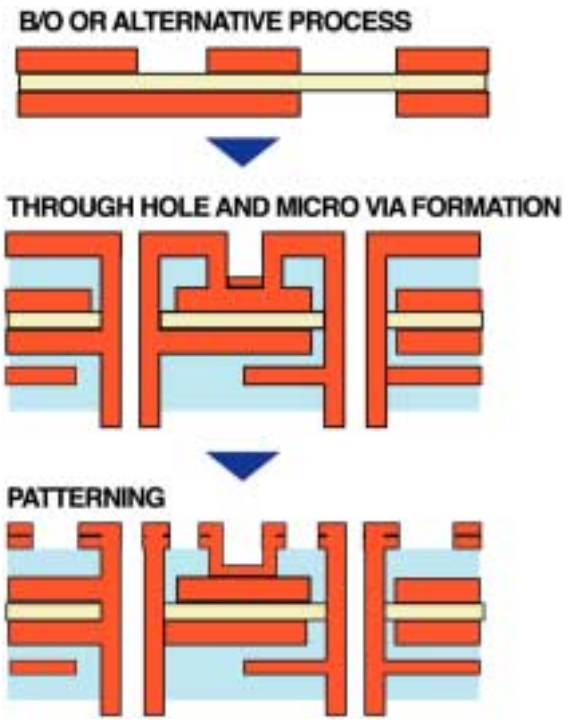
6. Lamination
- Standard Pre-baking, ex) 110C, 1-2hrs
- Standard process, compatible with FR-4 prepregs
- Scaling equivalent to ZBC2000

7. Drilling(Mechanical / Laser)
- Standard process

8. De-smearing
- Standard permanganate process, Atotech, Shipley etcs

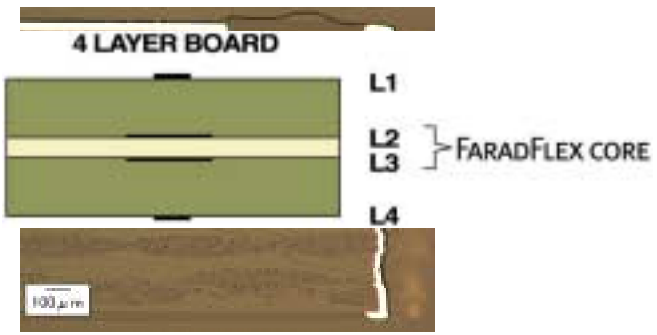
9. Plating
- Standard process

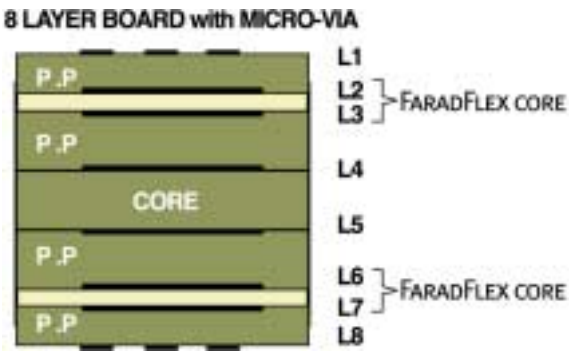


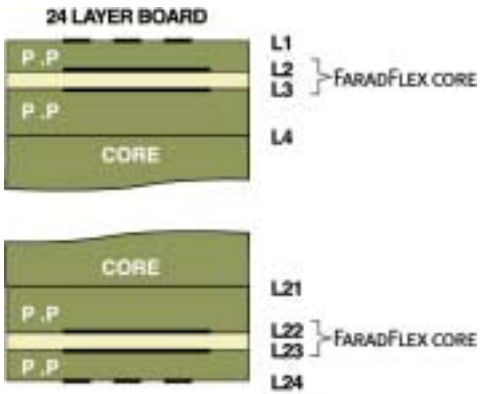


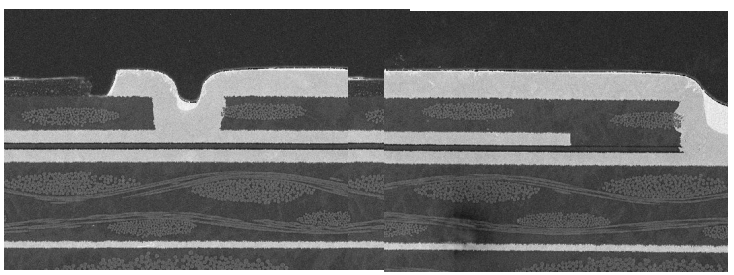
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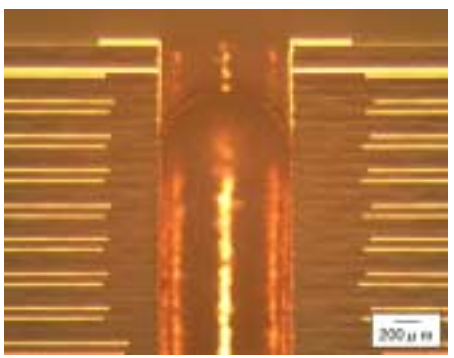
PWB examples using *FARADFLEX*











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